03-25-1998



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IN THE UNITED S

100672250

REQUEST FOR ASSIGNMENT RECORDAL

Box Assignments Honorable Commissioner of Patents and Trademarks Washington, D.C. 20231

Dear Sir:

Please record the attached assignment document.

1. Name of conveying party: KENJI KAWANO

2. Name and address of <u>Mitsubishi Denki Kabushiki Kaisha</u> receiving party: <u>2-3, Marunouchi 2-chome,</u>

chiyoda-ku, Tokyo 100-8310

<u>JAPAN</u>

3. Nature of conveyance: Assignment

Execution Date: March 16, 1998

4. Application No.:

The execution date of the patent application is March 16, 1998.

5. Name and address of party to whom correspondence concerning the attached document should be mailed:

LEYDIG, VOIT & MAYER
Suite 300
700 Thirteenth Street, N.W.
Washington, D.C. 20005

03/24/1998 SCHAPMAN 00000004 09044002 02 FC:581 40.00 OP

72846/SHINSEI

PATENT REEL: 9050 FRAME: 0538

- 6. Total number of patent applications involved: 1
- 7. Total fee:

\$40.00

- [X] Enclosed
- [X] The Commissioner is authorized to charge any deficiencies in the fee payment accompanying this communication and to credit any excess payment of fees to Deposit Account No. 12-1216.
- 8. Statement and signature

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Date

Registration No. 29,458

Total number of pages comprising cover sheet, attachments and document: 3

ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned,			
Kenji	Kawano, residing at Tokyo, Japan		
hereby sell, assign and transfer to MITSUBISHI DENKI KABUSHIKI KAISHA of 2-3, Marunouchi 2-chome, Chiyoda-ku, Tokyo 100-8310 Japan (hereinafter called the Assignee), its successors and assigns, the entire right, title, and interest in and to:			
		(i)	the application for United States Letters Patent entitled "SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE AND METHOD OF TESTING THE SAME"
			which was executed by the undersigned on March 16, 1998
			or filed on and accorded Serial No
	(hereinafter called the Application);		
(ii)	any and all inventions and improvements which are described in the Application;		
(iii)	any and all United States Letters Patents which may be granted on the Application (hereinafter called the Patent);		
(iv)	any and all divisions, continuations, substitutes, or reissues of the Application or Patent; and		
(v)	all benefits under the International Convention for the Protection of Industrial Property.		
It is hereby authorized that the above-mentioned assignee insert in this instrument the filing date and serial number of said application.			
It is hereby authorized and requested that the Commissioner of Patents issue any and all of said Letters Patent, when granted, to said Assignee.			
Further, it is agreed that, when requested, without charge to but at the expense of said Assignee, the undersigned will execute all divisional, continuing, substitute, or reissue patent applications, execute all additional assignments and other writings and provide all reasonable assistance requested by the Assignee.			
Signed at Tokyo, Japan			
this 16th day of March, 1998.			
WITNESS(ES): INVENTOR(S):			
	Menii Kayano		
	Kenji Kayano Kenji Kawano		

RECORDED: 03/19/1998

PATENT REEL: 9050 FRAME: 0540